

# NC-559-V2

LEADED SOLDERING LEAD SOLDER PASTE NO CLEAN SOLDER PASTE

# **PRODUCT APPLICATION & HIGHLIGHTS**

- i RELO flux classification
- Exceptional print definition at high printing speeds up to 100mm/sec
- Long stencil life
- Wide process window
- Clear residue
- Low voiding

- i Excellent wetting compatibility on most board finishes
- i Compatible with enclosed print heads
- Print & Dispense grade solder paste available

## **COMPATIBLE ALLOYS**

| ALLOY               | TEMPERATURE °C | TEMPERATURE °F |
|---------------------|----------------|----------------|
| 63Sn/37Pb           | 183            | 361            |
| 62Sn/36Pb/2Ag       | 179            | 354            |
| 62.8Sn/36.8Pb/0.4Ag | 179-183        | 354-361        |
| 60Sn/40Pb           | 183-191        | 361-376        |
| 43Sn/43Pb/14Bi      | 144-163        | 291-325        |

Custom alloys available. Contact us for availability.

## **TEST RESULTS**

| TEST J-STD-004 OR OTHER<br>REQUIREMENTS (AS STATED)               | TEST REQUIREMENT                                    | RESULT  |
|---|---|---|
| Copper Mirror   | IPC-TM-650: 2.3.32                                  | L: No breakthrough                                    |
| Corrosion   | IPC-TM-650: 2.6.15                                  | L: No corrosion                                       |
| Quantitative Halides  | IPC-TM-650: 2.3.28.1                                | L: <0.5%  |
| Electrochemical Migration   | IPC-TM-650: 2.6.14.1                                | L: <1 decade drop (no-clean)                          |
| Surface Insulation Resistance<br>85°C, 85% RH@ 168 Hours          | IPC-TM-650: 2.6.3.7                                 | L: 100 M (no-clean)                                   |
| Tack Value  | IPC-TM-650: 2.4.44                                  | 35g   |
| Viscosity - Malcom @ 10 RPM/25°C<br>(x103mPa/s) - Sn63/Pb37 T3/T4 | IPC-TM-650: 2.4.34.4                                | Print: 195-300<br>Dispensing: 100-140                 |
| Visual  | IPC-TM-650: 3.4.2.5                                 | Clear and free from precipitation                     |
| Conflict Minerals Compliance                                      | Electronic Industry Citizenship<br>Coalition (EICC) | Compliant   |
| REACH Compliance  | Articles 33 and 67 of regulation (EC) No 1907/2006  | May contain up to 1% w/w of ethoxylated 4-nonylphenol |

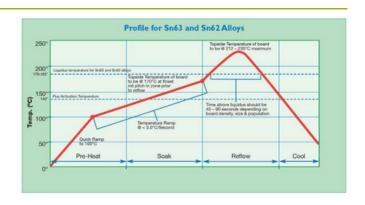
AMTECH™ NC-559-V2

### PROCESS RECOMMENDATION

The best process will depend on factors such as operating conditions, equipment, board or component design. Our team is ready to advise you.

#### **REFLOW GUIDELINE**

This profile is designed to serve as a starting point for process optimization. To achieve better results with voiding or to reduce tombstoning, consider using a longer soaking zone, for 60-90 seconds, with a rapid pre-heat stage. If there is evidence of solder de-wetting, consider lowering the peak reflow temperature, or reduce the time above liquidus to <90 seconds.



## **CLEANING POST SOLDERING**

This product is a no-clean solder paste, so cleaning is not required to meet IPC standards. The chemistry is specially designed so that any remaining flux residue is chemically inert and will not impact your assembled board or packaging under normal conditions. However, when cleaning is desired or required (e.g. high reliability assembly or to improved conformal coating adhesion), the flux residue can be easily removed with INVENTEC's own formulated flux cleaners.

> Inventec has over 60 years' experience in high-tech cleaning for aqueous and solvent based systems. Our solder materials are aligned with our cleaning solutions, which guarantees excellent cleaning with our materials.

| PROCESS TYPE                 | DEFLUXING SOLUTIONS  |  |
|------------------------------|--|--|
| Manual                       | Quicksolv™ DEF90, Quicksolv™ DEF70, Promoclean™ TP61                   |  |
| Aqueous (Immersion or spray) | Promoclean™ DISPER 607, Promoclean™ DISPER 707, Promoclean™ DISPER 800 |  |
| Co-solvent                   | Topklean™ EL 80 + Promosolv™ rinsing solvents                          |  |
| Mono-solvent (vapor phase)   | Promosolv™ 70ES, Promosolv™ 70IS                                       |  |

Other products available, depending on specific customer requirements. Check also our maintenance cleaning solutions.

#### PRINTER OPERATION

The following are general guidelines for stencil printer optimization with NC-559-V2. Some adjustments may be necessary based on your process requirements.

i Print Speed: 25-100 mm/sec

Squeegee Pressure: 70-250g/cm of blade

Under Stencil Wipe: Once every 10-25 prints, or as necessary

# STENCIL LIFE

i > 8 hours @ 30-45% RH and 20-25°C

~ 4 hours @ 45~75% RH and 20-25°C

## **Amtech Low Oxide Power Distribution**

| Micron Size | Туре   | Pitch Requirements |
|-------------|--------|--------------------|
| 45-75μ      | Type-2 | 24 mil and above   |
| 25-45μ      | Type-3 | 16-24 mil          |
| 20-38μ      | Type-4 | 12-16 mil          |
| 15-25μ      | Type-5 | 8-12 mil           |
| 5-15μ       | Type-6 | 5-8 mil            |
| 2-11μ       | Type-7 | < 5 mil            |

Note: Type-6 and Type-7 may not be available in certain alloys. Other powder distributions are available on request.

## PACKAGING, STORAGE & SHELF LIFE

Solder paste should be stored between 3-8 °C (37-46 °F) to obtain the maximum refrigerated shelf life of six months. Unopened solder paste stored at room temperature, 25 °C (77°F) will have a one month shelf life. Syringes and cartridges should be stored vertically in the refrigerator with the dispensing tip down. Allow 4-8 hours for solder paste to reach an operating temperature of 20-25 °C (68-77°F). Keep the solder paste container sealed while warming the solder paste to operating temperature. NEVER FREEZE SOLDER PASTE.

#### **AVAILABLE PACKAGING**



**SYRINGE** 10cc (35g)







AMTECH™ NC-559-V2 PDS2025-EN

## **HEALTH, SAFETY & ENVIRONMENT**

No issues when used as recommended. In accordance with the Annex II of Directive 2011/65/UE (RoHS), including its amendments, we certify that this product does not contains quantities above 0.1% of Hg, Pb, Cr VI, PBB, PBDE, DEHP, BBP, DBP, DIBP and above 0.01% of Cd. INVENTEC PERFORMANCE CHEMICALS also fulfills its direct obligations under the REACH and Conflict Mineral regulations. Please refer always to the Safety Data Sheet (SDS or MSDS) prior to use. Our SDS can be downloaded at www.quickfds.com. We will request to provide your email address, so we can automatically send you a new version of the SDS when a future update would occur.

### TECHNICAL SUPPORT & FREE-OF-CHARGE TESTING

Inventec has a worldwide dedicated Technical Support team to help you along the various stages of our cooperation.

- Depending on your request, we provide online or onsite support:

  ¡ To select the right product based on your specific needs
  - † To assist you in your product qualification process
  - i To guide you with the initial set up of your process at all your worldwide manufacturing facilities
  - i To provide fast response on technical issues which could occur at any time during mass production

When flux cleaning is necessary, customers are welcome to visit our CLEANING CENTERS to witness the process firsthand and experience the effectiveness of our solutions. We offer both aqueous- and solvent-based processes.

Inventec is unique in the world by developing not only cleaning materials but also soldering and coating solutions. These materials are very closely linked with each other from a process point of view. Talking to our Technical Team, who understands very well these 3 different product groups, will help you greatly to overcome technical challenges within your overall process.

Contact our technical support via contact@inventec.dehon.com or your local sales representative.

### **ABOUT INVENTEC & AMTECH**

Inventec<sup>™</sup> is a global provider of SOLDERING, CLEANING, COATING, COOLING materials for Electronic, Semiconductor and Industrial applications. For over 60 years we have shown leadership in innovation by putting HEALTH IMPACT, SUSTAINABILITY and RELIABILITY at the core of our product development.

With ISO 9001 & 14001 production sites in France, Switzerland, USA, Mexico, Malaysia and China we can guarantee a smooth and cost-effective supply chain.

We supply to many industries but the excellent performance of our products in applications which demand high reliability, leads us to focus especially on the AUTOMOTIVE, AEROSPACE, SEMICONDUCTOR, ENERGY and MEDICAL industry.

Inventec<sup>™</sup> acquired AMTECH<sup>™</sup> in 2014, from where it received the rights to manufacture and commercialize the AMTECH<sup>™</sup> product range. Inventec<sup>™</sup> will remain supplying AMTECH<sup>™</sup> products to our worldwide customers by aligning to our Inventec<sup>™</sup> branding policy. If you are in doubt that you are buying genuine AMTECH<sup>™</sup> product, contact us to check if your supply source is an authorized distributor or reseller. AMTECH<sup>™</sup> products are produced in the USA.



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**SOLDERING** 

**CLEANING** 

**COATING** 

COOLING

This data is based on information that the manufacturer believes to be reliable and offered in good faith. In no event will INVENTEC PERFORMANCE CHEMICALS be responsible for special, incidental and consequential damages. The user is responsible to the Administrative Authorities (regulations for the protection of the Environment) for the conformity of his installation.

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